

2SK2865

Chopper Regulator, DC/DC Converter and Motor Drive Applications

- Low drain-source ON-resistance : $R_{DS(ON)} = 4.2 \Omega$ (typ.)
- High forward transfer admittance : $|Y_{fs}| = 1.7 \text{ S}$ (typ.)
- Low leakage current : $I_{DSS} = 100 \mu\text{A}$ (max) ($V_{DS} = 600 \text{ V}$)
- Enhancement mode : $V_{th} = 2.0\sim 4.0 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristic		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	600	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	600	V
Gate-source voltage		V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	2	A
	Pulse ($t = 1 \text{ ms}$) (Note 1)	I_{DP}	5	A
	Pulse ($t = 100 \mu\text{s}$) (Note 1)	I_{DP}	8	A
Drain power dissipation ($T_c = 25^\circ\text{C}$)		P_D	20	W
Single-pulse avalanche energy (Note 2)		E_{AS}	93	mJ
Avalanche current		I_{AR}	2	A
Repetitive avalanche energy (Note 3)		E_{AR}	2	mJ
Channel temperature		T_{ch}	150	$^\circ\text{C}$
Storage temperature range		T_{stg}	$-55\sim 150$	$^\circ\text{C}$

Thermal Characteristics

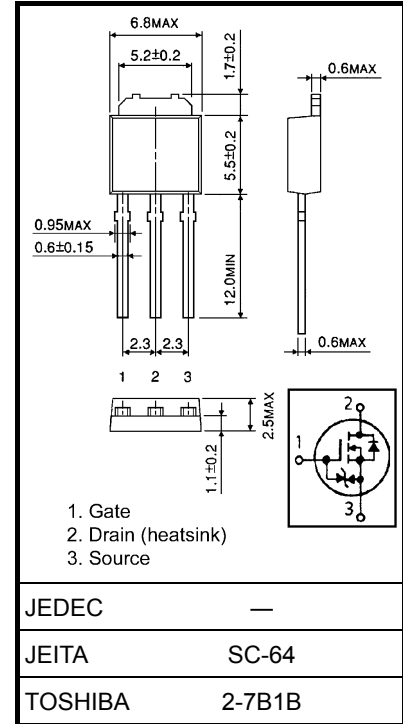
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	6.25	$^\circ\text{C} / \text{W}$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	125	$^\circ\text{C} / \text{W}$

Note 1: Ensure that the channel temperature does not exceed 150°C .

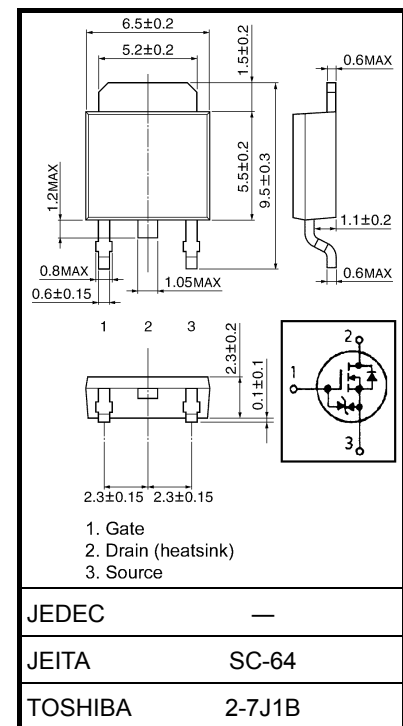
Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 41 \text{ mH}$, $R_G = 25 \Omega$, $I_{AR} = 2 \text{ A}$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

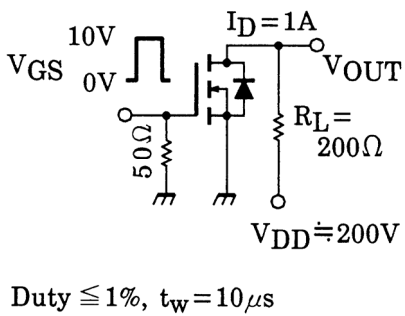
Unit: mm



Weight: 0.36 g (typ.)



Weight: 0.36 g (typ.)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	—	—	± 10	μA
Gate-source breakdown voltage		$V_{(BR)GSS}$	$I_G = \pm 10 \mu\text{A}, V_{DS} = 0 \text{ V}$	± 30	—	—	V
Drain cutoff current		I_{DSS}	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	600	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$	2.0	—	4.0	V
Drain-source ON-resistance		$R_{DS(ON)}$	$V_{GS} = 10 \text{ V}, I_D = 1 \text{ A}$	—	4.2	5.0	Ω
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ A}$	0.8	1.7	—	S
Input capacitance		C_{iss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	—	380	—	pF
Reverse transfer capacitance		C_{rss}		—	40	—	
Output capacitance		C_{oss}		—	120	—	
Switching time	Rise time	t_r		—	15	—	ns
	Turn-on time	t_{on}		—	25	—	
	Fall time	t_f		—	20	—	
	Turn-off time	t_{off}		—	80	—	
Total gate charge (gate-source plus gate-drain)		Q_g	$V_{DD} \approx 480 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$	—	9	—	nC
Gate-source charge		Q_{gs}		—	5	—	
Gate-drain ("Miller") charge		Q_{gd}		—	4	—	

Source-Drain Ratings and Characteristics ($T_a = 25^\circ\text{C}$)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	2	A
Pulse drain reverse current (Note 1)	I_{DRP}	$t = 1 \text{ ms}$	—	—	5	A
	I_{DRP}	$t = 100 \mu\text{s}$	—	—	8	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 2 \text{ A}, V_{GS} = 0 \text{ V}$	—	—	-1.5	V
Reverse recovery time	t_{rr}	$I_{DR} = 2 \text{ A}, V_{GS} = 0 \text{ V}$	—	1000	—	ns
Reverse recovery charge	Q_{rr}	$dI_{DR} / dt = 100 \text{ A} / \mu\text{s}$	—	3.5	—	μC

Marking

